

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	639	(copper or cu) and wiring and pattern\$4 and laminat\$3 and ("ferric chloride" or "cupic chloride") and (resin or seal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 10:30
L2	965	(copper or cu) same wiring same pattern\$4 same laminat\$3 same (resin or seal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 10:17
L4	92	2 and electrode and (mask or resist)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/06 10:20
L5	658	(metal or metallization) and wiring and (pattern\$4 or etch\$3) and laminat\$3 and ("ferric chloride" or "cupic chloride") and (resin or seal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 10:32
L6	408	5 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 10:34
L7	69	igarashi-yusuke.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 10:34
L8	448	sakamoto-noriaki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/06 10:35